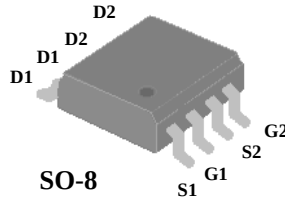


- ▼ Low On-Resistance
- ▼ Fast Switching Speed
- ▼ Surface Mount Package
- ▼ RoHS Compliant & Halogen-Free

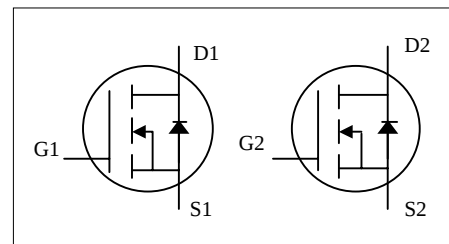


BV_{DSS}	40V
$R_{DS(ON)}$	20m Ω
I_D	7.8A

Description

XP9960 series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The SO-8 package is widely preferred for all commercial-industrial surface mount applications using infrared reflow technique and suited for voltage conversion or switch applications.



Absolute Maximum Ratings@ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^{\circ}\text{C}$	Drain Current, $V_{GS} @ 10V^3$	7.8	A
$I_D@T_A=70^{\circ}\text{C}$	Drain Current, $V_{GS} @ 10V^3$	6.2	A
I_{DM}	Pulsed Drain Current ¹	20	A
$P_D@T_A=25^{\circ}\text{C}$	Total Power Dissipation	2	W
	Linear Derating Factor	0.016	W/ $^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-amb}$	Maximum Thermal Resistance, Junction-ambient ³	62.5	$^{\circ}\text{C}/\text{W}$

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	40	-	-	V
ΔBV _{DSS} /ΔT _j	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D =1mA	-	0.032	-	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =7A	-	-	20	mΩ
		V _{GS} =4.5V, I _D =5A	-	-	32	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	-	3	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =7A	-	25	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =40V, V _{GS} =0V	-	-	1	uA
	Drain-Source Leakage Current (T _j =70°C)	V _{DS} =32V, V _{GS} =0V	-	-	25	uA
I _{GSS}	Gate-Source Leakage	V _{GS} = ±20V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge	I _D =7A	-	14.7	-	nC
Q _{gs}	Gate-Source Charge	V _{DS} =20V	-	7.1	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =4.5V	-	6.8	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =20V	-	11.5	-	ns
t _r	Rise Time	I _D =1A	-	6.3	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω, V _{GS} =10V	-	28.2	-	ns
t _f	Fall Time	R _D =20Ω	-	12.6	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	1725	-	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	235	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	145	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I _S	Continuous Source Current (Body Diode)	V _D =V _G =0V, V _S =1.3V	-	-	1.54	A
V _{SD}	Forward On Voltage ²	T _j =25°C, I _S =2.3A, V _{GS} =0V	-	-	1.3	V

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse width ≤300us, duty cycle ≤2%.
- 3.Surface mounted on 1 in² copper pad of FR4 board, t ≤10sec; 135°C/W when mounted on Min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

XSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

XSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

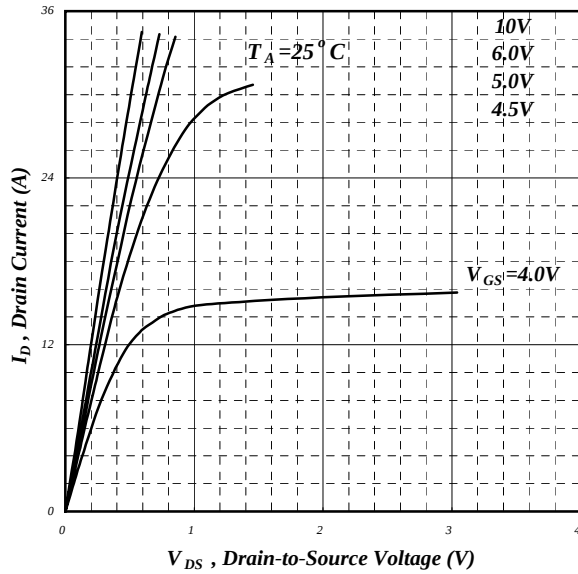


Fig 1. Typical Output Characteristics

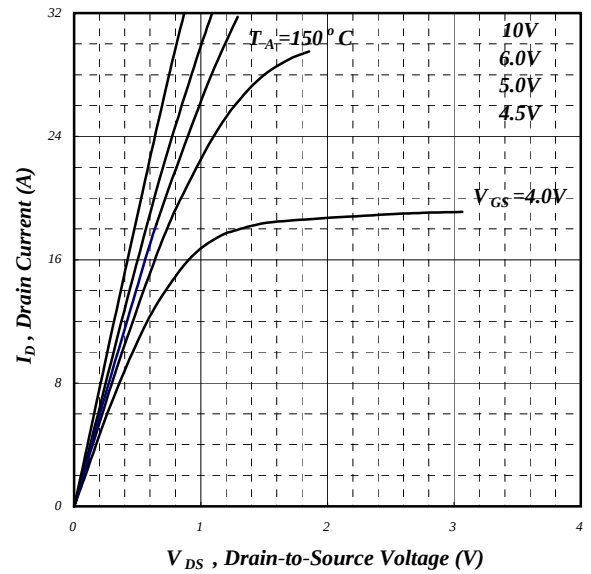


Fig 2. Typical Output Characteristics

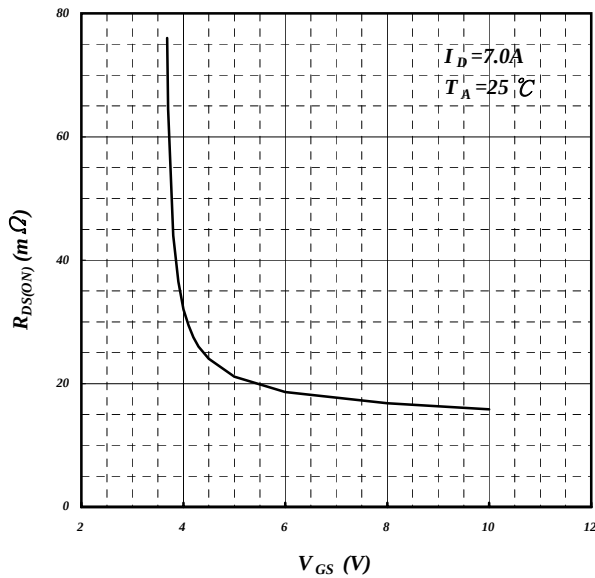
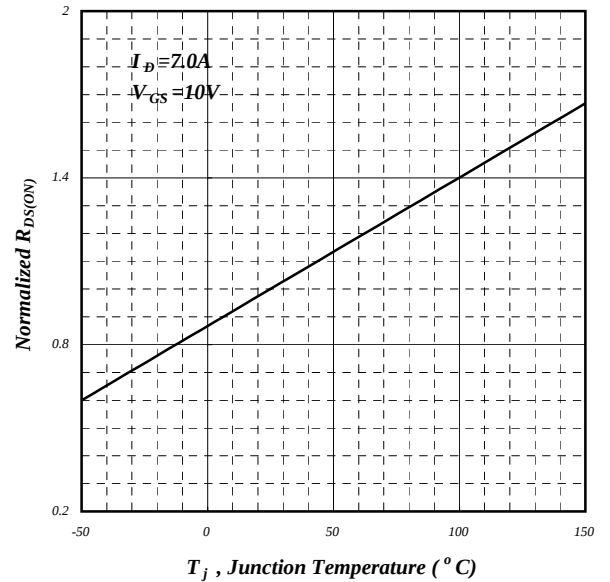


Fig 3. On-Resistance v.s. Gate Voltage



**Fig 4. Normalized On-Resistance
v.s. Junction Temperature**

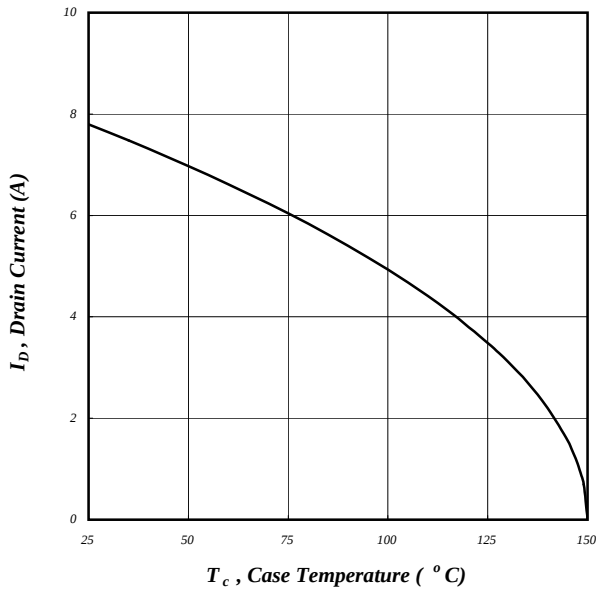


Fig 5. Maximum Drain Current v.s. Case Temperature

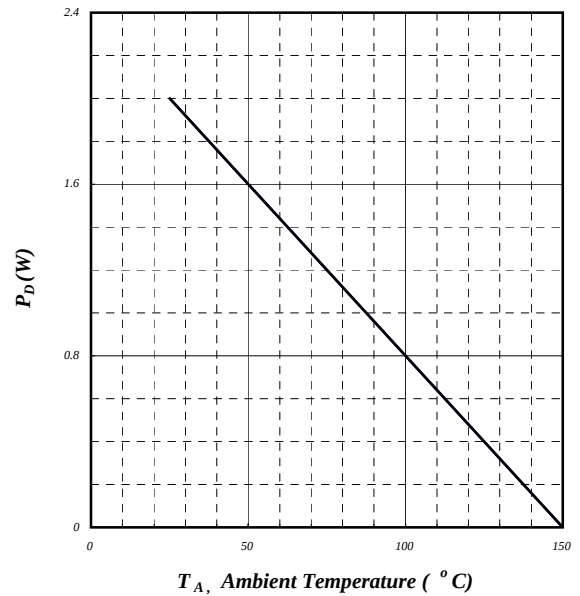


Fig 6. Typical Power Dissipation

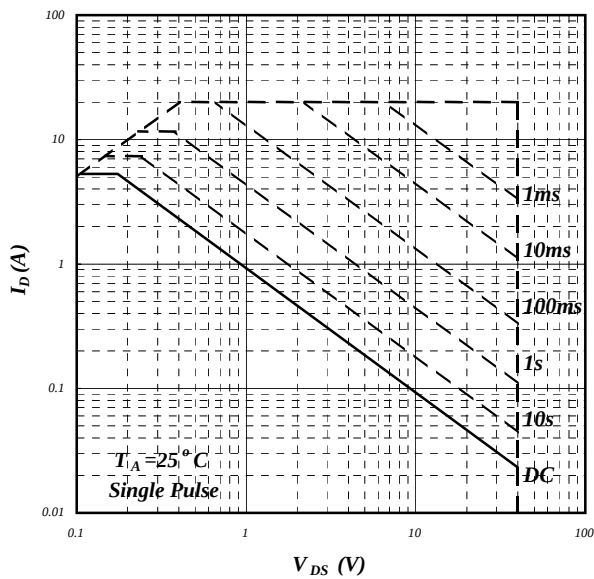


Fig 7. Maximum Safe Operating Area

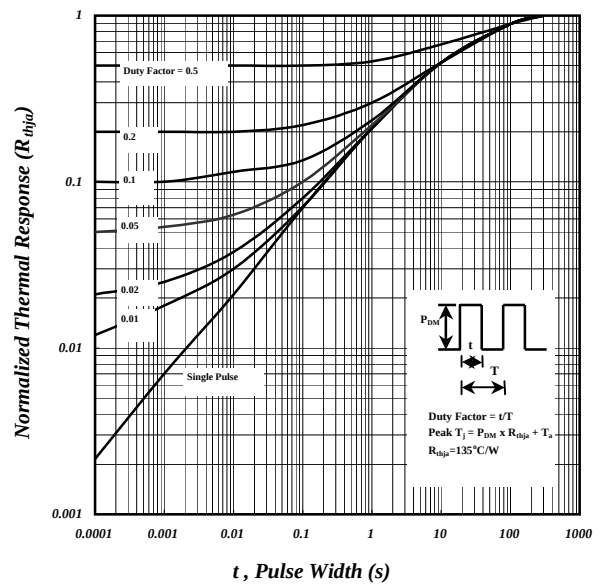
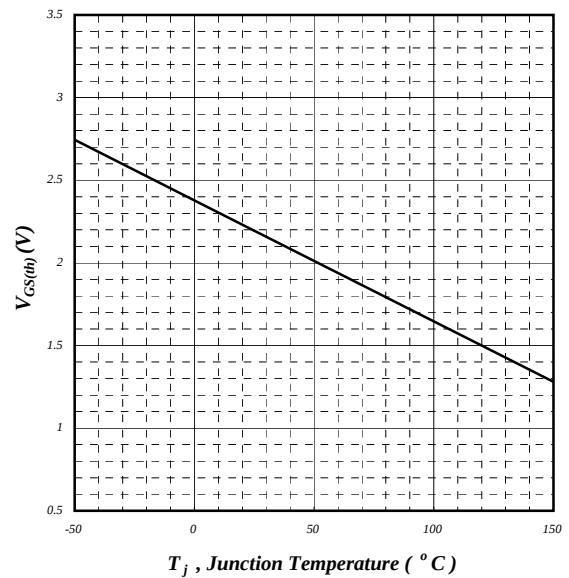
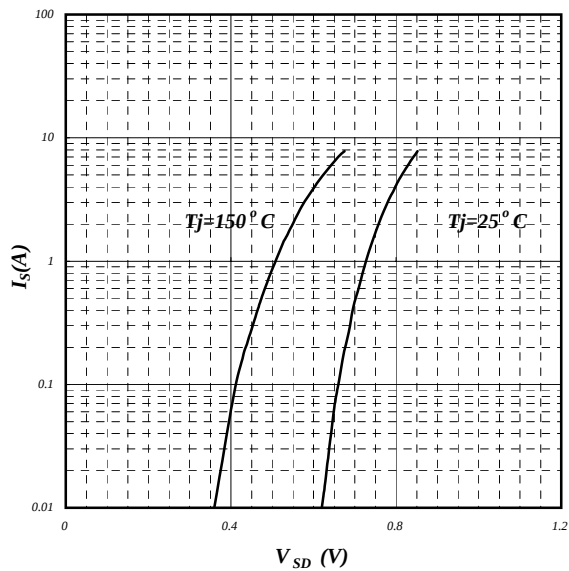
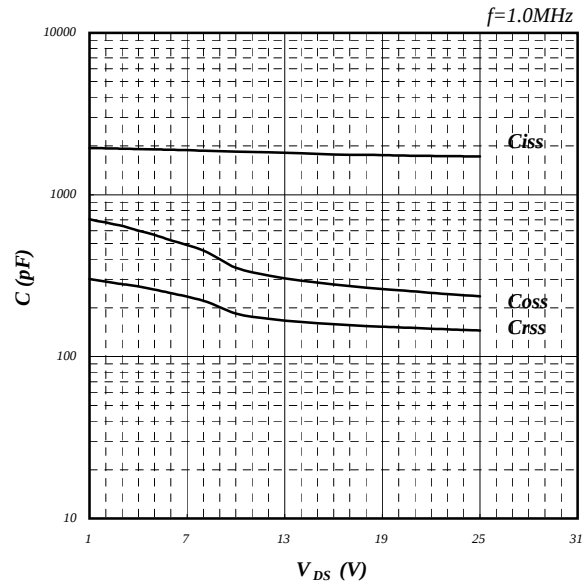
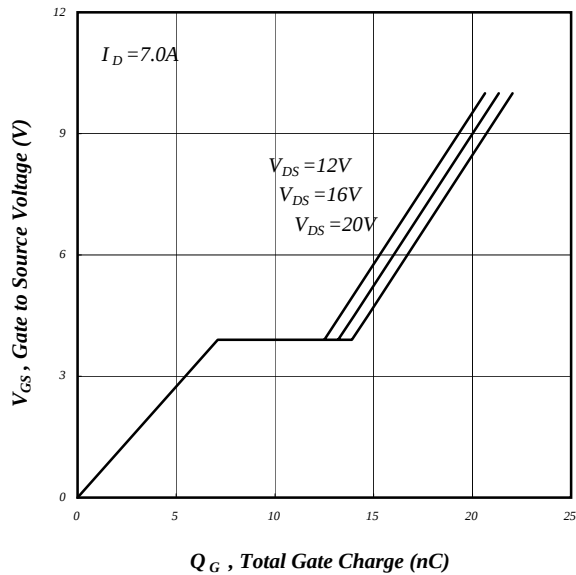


Fig 8. Effective Transient Thermal Impedance



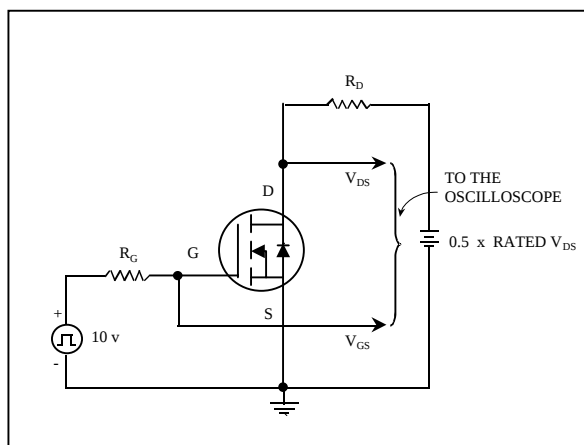


Fig 13. Switching Time Circuit

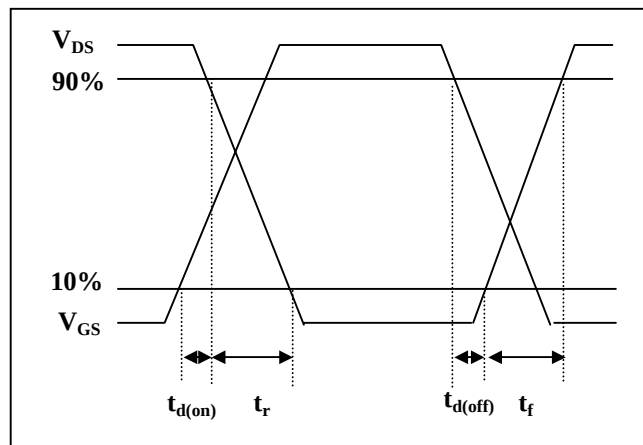


Fig 14. Switching Time Waveform

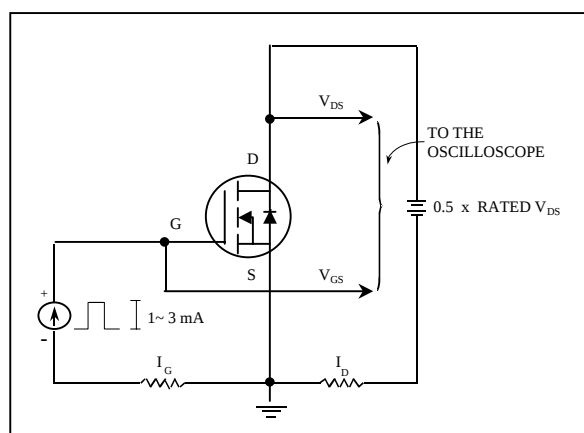


Fig 15. Gate Charge Circuit

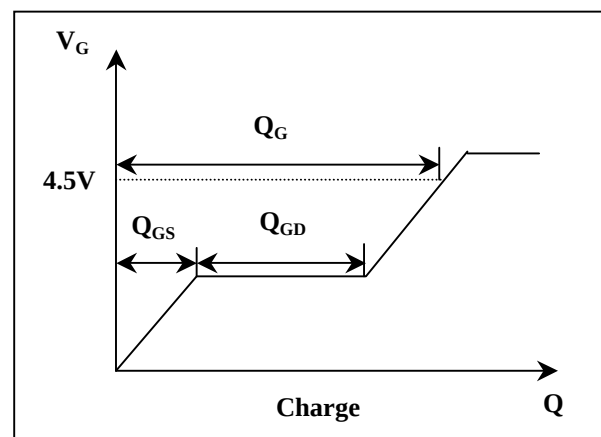
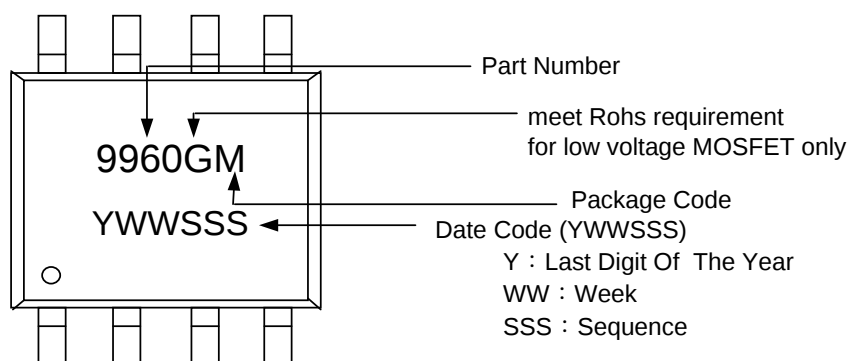
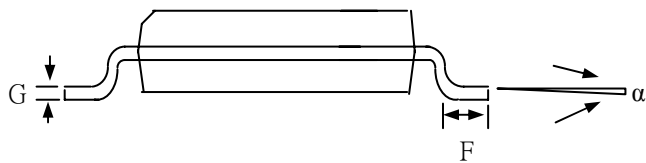
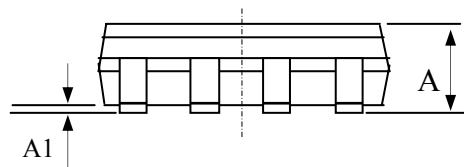
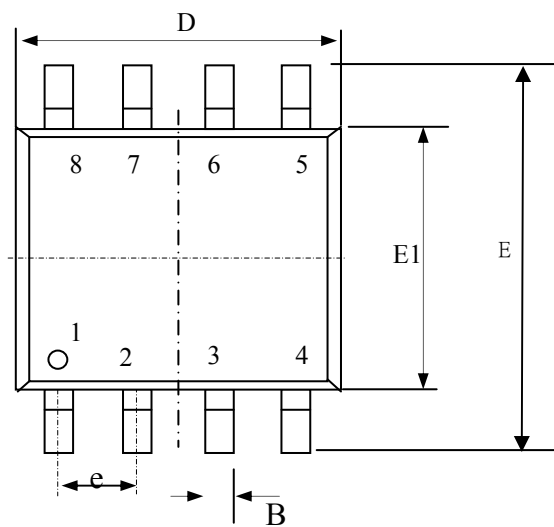


Fig 16. Gate Charge Waveform

MARKING INFORMATION



Package Outline : SO-8



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.05	0.15	0.25
B	0.30	0.41	0.51
D	4.80	5.05	5.30
E	5.79	6.00	6.20
E1	3.70	3.90	4.10
e	1.27 TYP		
G	0.17	0.21	0.25
F	0.38	0.83	1.27
α	0°	4°	8°

- 1.All Dimension Are In Millimeters.
- 2.Dimension Does Not Include Mold Protrusions.

SO-8 FOOTPRINT :

